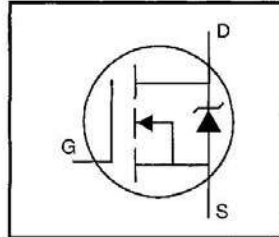


# IRFP264PbF

## HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

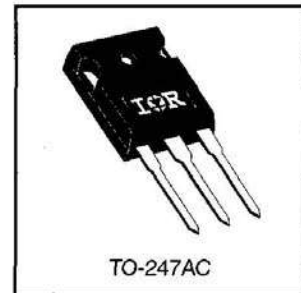


$V_{DSS} = 250V$
$R_{DS(on)} = 0.075\Omega$
$I_D = 38A$

### Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-247 package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting hole. It also provides greater creepage distance between pins to meet the requirements of most safety specifications.



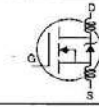
### Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10 V$	38	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10 V$	24	
$I_{DM}$	Pulsed Drain Current ①	150	
$P_D @ T_C = 25^\circ C$	Power Dissipation	280	W
	Linear Derating Factor	2.2	W/°C
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy ②	1000	mJ
$I_{AR}$	Avalanche Current ①	38	A
$E_{AR}$	Repetitive Avalanche Energy ①	28	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.8	V/ns
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf·in (1.1 N·m)	

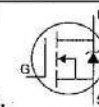
### Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	0.45	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	40	

### Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	250	—	—	V	$V_{GS}=0V, I_D=250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.37	—	V/°C	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.075	$\Omega$	$V_{GS}=10V, I_D=23A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
$g_{fs}$	Forward Transconductance	20	—	—	S	$V_{DS}=50V, I_D=23A$ ④
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	25	$\mu A$	$V_{DS}=250V, V_{GS}=0V$
		—	—	250		$V_{DS}=200V, V_{GS}=0V, T_J=125^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS}=20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS}=-20V$
$Q_g$	Total Gate Charge	—	—	210	nC	$I_D=38A$
$Q_{gs}$	Gate-to-Source Charge	—	—	35		$V_{DS}=200V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge	—	—	98		$V_{GS}=10V$ See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	22	—	ns	$V_{DD}=125V$ $I_D=38A$ $R_G=4.3\Omega$ $R_D=3.2\Omega$ See Figure 10 ④
$t_r$	Rise Time	—	99	—		
$t_{d(off)}$	Turn-Off Delay Time	—	110	—		
$t_f$	Fall Time	—	92	—		
$L_D$	Internal Drain Inductance	—	5.0	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact 
$L_S$	Internal Source Inductance	—	13	—		
$C_{iss}$	Input Capacitance	—	5400	—	pF	$V_{GS}=0V$
$C_{oss}$	Output Capacitance	—	870	—		$V_{DS}=25V$
$C_{rss}$	Reverse Transfer Capacitance	—	150	—		$f=1.0\text{MHz}$ See Figure 5

### Source-Drain Ratings and Characteristics

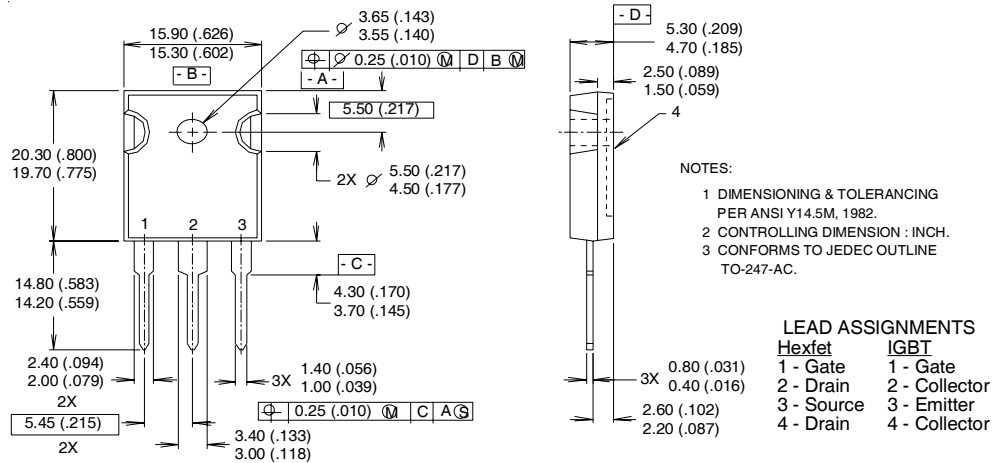
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	38	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	150		
$V_{SD}$	Diode Forward Voltage	—	—	1.8	V	$T_J=25^\circ\text{C}, I_S=38A, V_{GS}=0V$ ④
$t_{rr}$	Reverse Recovery Time	—	410	620	ns	$T_J=25^\circ\text{C}, I_F=38A$
$Q_{rr}$	Reverse Recovery Charge	—	5.7	8.6	$\mu C$	$di/dt=100A/\mu s$ ④
$t_{on}$	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S+L_D$ )				

#### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)
- ②  $V_{DD}=50V$ , starting  $T_J=25^\circ\text{C}$ ,  $L=1.1\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{AS}=38A$  (See Figure 12)
- ③  $I_{SD}\leq 38A$ ,  $di/dt\leq 210A/\mu s$ ,  $V_{DD}\leq V_{(BR)DSS}$ ,  $T_J\leq 150^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .

## TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



## TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30  
 WITH ASSEMBLY  
 LOT CODE 5657  
 ASSEMBLED ON WW 35, 2000  
 IN THE ASSEMBLY LINE "H"

**Note:** "P" in assembly line position indicates "Lead-Free"

